Thermal Film

Features:
Optional Fiberglass or Polyimide Film (PI film) as the substrate, coated on both sides with a mixture of thermal conductive fillers and silicone, offering high mechanical strength and high electrical insulation properties.

Applications:
Supplies (UPS), MOSFETs, switching power supplies, power amplifiers, electric vehicle motor controllers.

Model	Substrate	Thickness, mm	Thermal Conductivity W/m·K	Breakdown Voltage, AC	Hardness, Shore A	Operating Temp., ℃
JSSC-0800SG	Fiberglass	0.3~0.5	0.8	> 4 kV	45	-50~200
JSSC-0900FG	Fiberglass	0.23~0.5	2.0	> 4 kV	45	-50~200
JSSC-1000FG	Fiberglass	0.25~0.5	3.5	> 4 kV	90	-50~200
JSSC-0800PI-2-K4	PI Film	0.15	0.9	> 4 kV	90	-50~200
JSSC-0800PI-2-K6	PI Film	0.15	1.1	> 4 kV	90	-50~200
JSSC-0800PI-2-K10	PI Film	0.15	1.3	> 4 kV	90	-50~200